

Features

- Low On-Resistance
 - 70mΩ @V_{GS} = -4.5V
 - 85mΩ @V_{GS} = -2.5V
 - 86mΩ (typ) @V_{GS} = -1.8V
- Low Gate Threshold Voltage, -0.9V Max
- Fast Switching Speed
- Low Input/Output Leakage
- Low Profile, 0.5mm Max Height
- Lead Free/RoHS Compliant (Note 2)**
- "Green" Device (Note 3)**
- Qualified to AEC-Q101 Standards for High Reliability**

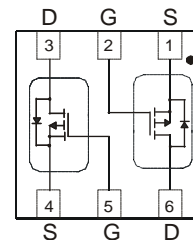
Mechanical Data

- Case: DFN2020B-6
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – NiPdAu annealed over Copper leadframe.
Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.0065 grams (approximate)

DFN2020B-6



BOTTOM VIEW



TOP VIEW
Internal Schematic

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P _D	1.4	W
Thermal Resistance, Junction to Ambient	R _{θJA}	89	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Maximum Ratings @T_A = 25°C unless otherwise specified

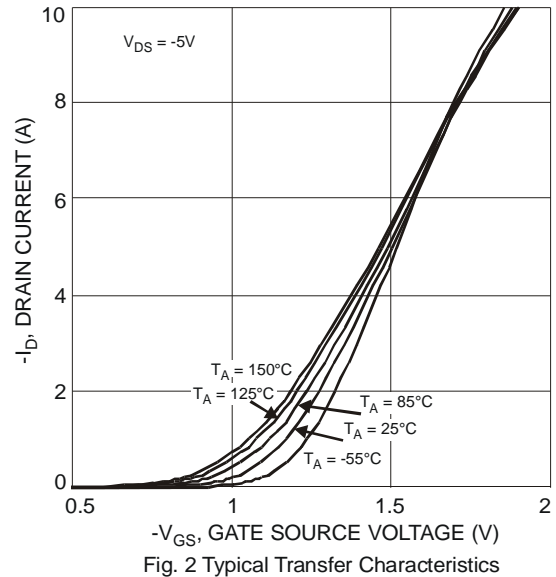
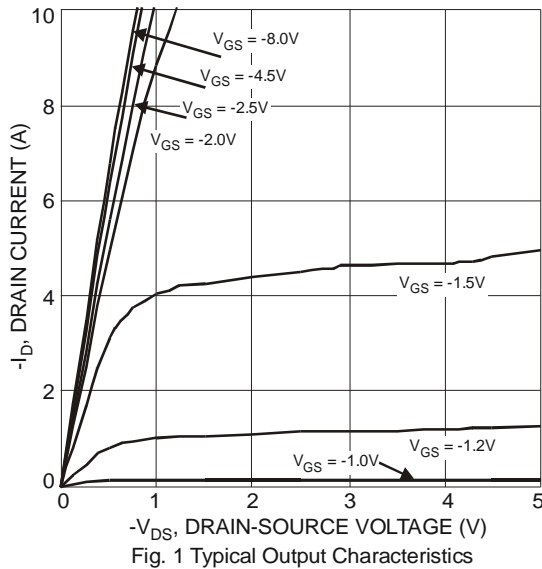
Characteristic	Symbol	Value	Units
Drain-Source Voltage	V _{DSS}	-20	V
Gate-Source Voltage	V _{GSS}	±12	V
Drain Current (Note 1)	I _D	-3.8	A
Pulsed Drain Current (Note 4)	I _{DM}	-13	A

- Notes:
- Device mounted on FR-4 PCB, on minimum recommended, 2oz Copper pad layout.
 - No purposefully added lead.
 - Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 - Repetitive rating, pulse width limited by junction temperature.

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV _{DSS}	-20	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	-1	μA	V _{DS} = -20V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100 ±800	nA	V _{GS} = ±8V, V _{DS} = 0V V _{GS} = ±12V, V _{DS} = 0V
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	-0.45	—	-0.9	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(on)}	—	54	70	mΩ	V _{GS} = -4.5V, I _D = -2.8A
		—	68	85		V _{GS} = -2.5V, I _D = -2.0A
		—	86	—		V _{GS} = -1.8V, I _D = -1.0A
Forward Transfer Admittance	Y _{fs}	—	8	—	S	V _{DS} = -5V, I _D = -2.8A
Diode Forward Voltage (Note 5)	V _{SD}	—	0.7	-1.2	V	V _{GS} = 0V, I _S = -1.6A
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	—	536	—	pF	V _{DS} = -10V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	68	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	59	—	pF	
Gate Resistance	R _g	-	8.72	-	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge	Q _g	-	6.5	-	nC	V _{GS} = -4.5V, V _{DD} = -10V, I _D = -1.5A
Gate-Source Charge	Q _{gs}	-	0.8	-	nC	
Gate-Drain Charge	Q _{gd}	-	1.4	-	nC	
Turn-On Delay Time	t _{D(on)}	-	11.51	-	ns	V _{GEN} = -4.5V, V _{DD} = -10V, R _L = 10Ω, R _G = 6Ω
Turn-On Rise Time	t _r	-	12.09	-	ns	
Turn-Off Delay Time	t _{D(off)}	-	55.34	-	ns	
Turn-Off Fall Time	t _f	-	27.54	-	ns	

Notes: 5. Short duration pulse test used to minimize self-heating effect.



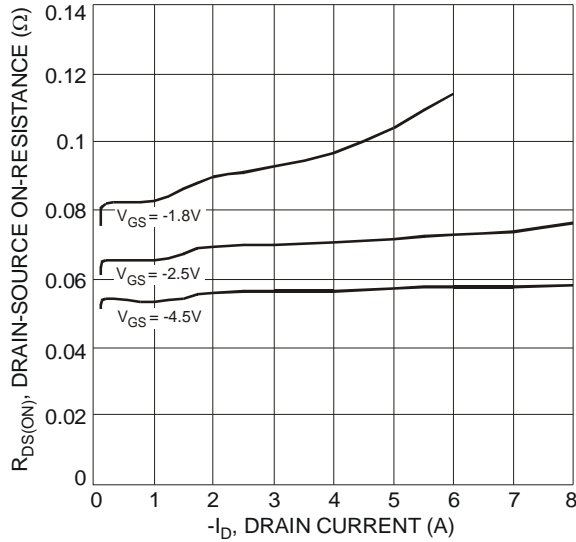


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

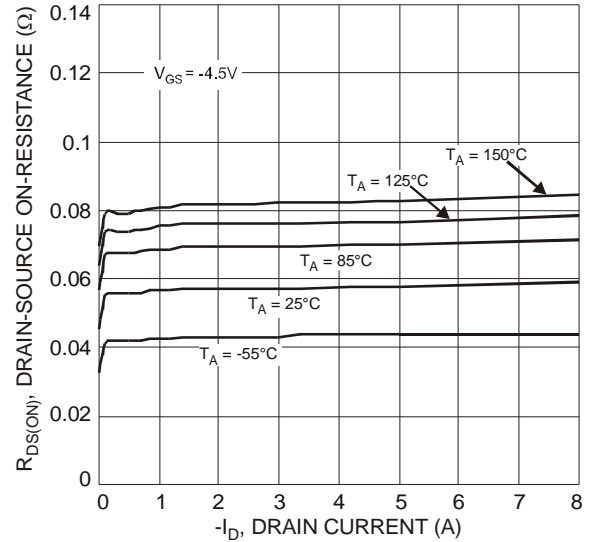


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

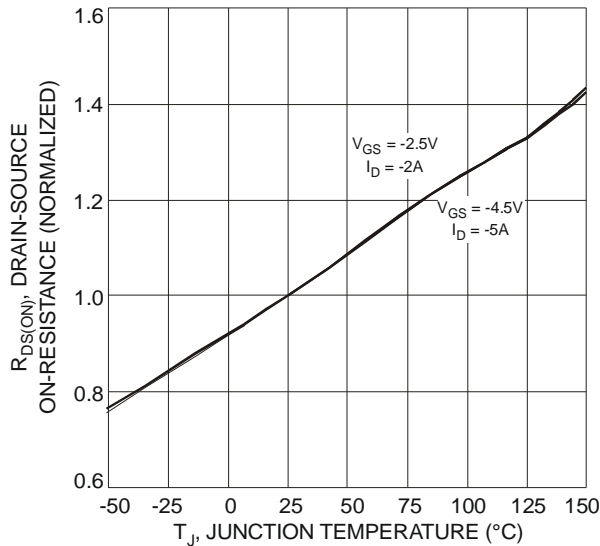


Fig. 5 On-Resistance Variation with Temperature

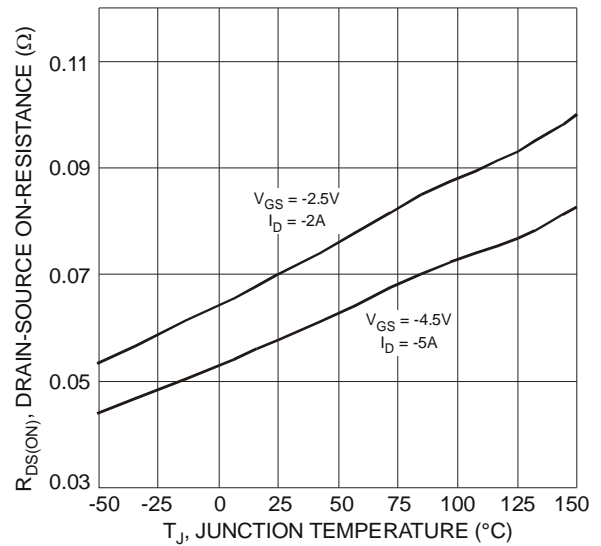


Fig. 6 On-Resistance Variation with Temperature

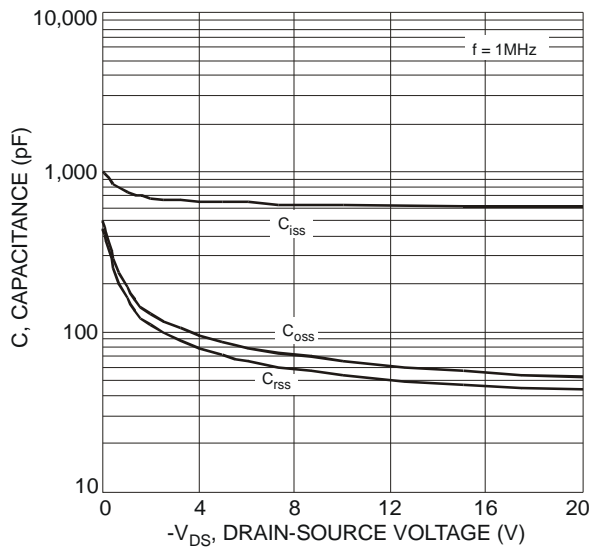


Fig. 7 Typical Capacitance

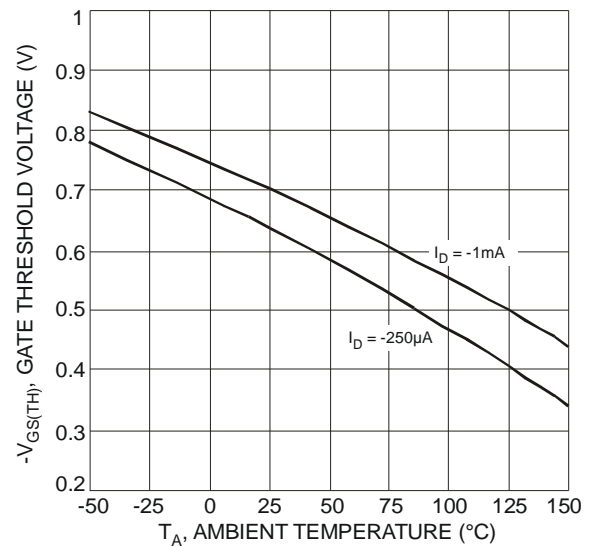
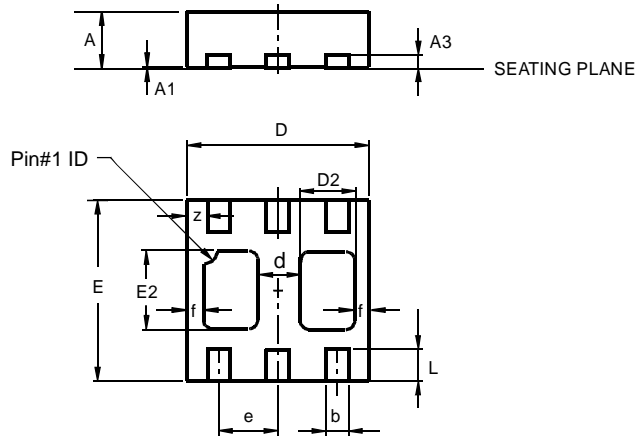


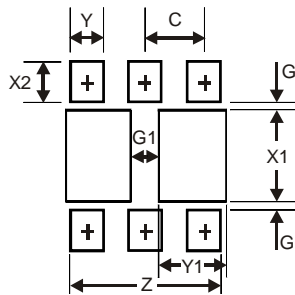
Fig. 8 Gate Threshold Variation vs. Ambient Temperature

Package Outline Dimensions



DFN2020B-6			
Dim	Min	Max	Typ
A	0.545	0.605	0.575
A1	0	0.05	0.02
A3	—	—	0.13
b	0.20	0.30	0.25
D	1.95	2.075	2.00
d	—	—	0.45
D2	0.50	0.70	0.60
e	—	—	0.65
E	1.95	2.075	2.00
E2	0.90	1.10	1.00
f	—	—	0.15
L	0.25	0.35	0.30
z	—	—	0.225
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Y	0.37
Y1	0.70
C	0.65

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